

What is claimed is:

1. A polishing pad installation tool comprising:
 - a base portion;

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at least one compressible layer in operative connection with the base portion, wherein the compressible layer includes an upper surface, and wherein the compressible layer includes a plurality of apertures through the upper surface of the compressible layer;

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a plurality of parallel pins in operative connection with the base portion, wherein the pins extend outwardly through the apertures of the compressible layer, wherein each pin includes a collar portion in surrounding relation about each pin, wherein when the compressible layer is in an uncompressed condition, the collar portions of each pin do not extend above the upper surface of the compressible layer.

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2. The polishing pad installation tool according to claim 1, wherein the pins are positioned on the base in a pattern which corresponds to the holes in a polishing platen.

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3. The polishing pad installation tool according to claim 2, wherein the pins have diameters which are smaller than the diameters of the holes in a polishing pad.

4. The polishing pad installation tool according to claim 3, wherein the collar portions of each pin have diameters larger than the diameters of the holes in the polishing pad.

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5. The polishing pad installation tool according to claim 4, wherein when the tool is placed adjacent the polishing pad the pins are operative to enter each of the holes of the polishing pad.

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6. The polishing pad installation tool according to claim 5, wherein at least two of the pins are king pins, and wherein the king pins are visually distinguishable from the pins that are not the king pins.

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7. The polishing pad installation tool according to claim 6, wherein the king pins are longer than the pins that are not king pins with respect to the base portion.

8. The polishing pad installation tool according to claim 7, wherein when the compressible layer is in the uncompressed condition, the king pins extend above the upper surface of the compressed layer.

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9. The polishing pad installation tool according to claim 5, wherein when the tool is pressed against the polishing pad the compressible layer is operative to compress between the base portion and a polishing surface of the polishing pad.

10. The polishing pad installation tool according to claim 5, wherein the collar portion of each pin includes an upper surface, wherein each pin extends above the collar portion.

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11. The polishing pad installation tool according to claim 10, wherein when the compressible layer is in the uncompressed condition, the upper surface of each collar portion is lower in height with respect to the base portion than the upper surface of the compressible layer.

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12. The polishing pad installation tool according to claim 5, wherein the collar portions are in sliding connection with the pins, and wherein the collar portions are biased to slide upwardly along the pins and away from the base portion.

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13. The polishing pad installation tool according to claim 12, further comprising springs in surrounding relation about the pins, wherein the springs are operative to bias the collar portions.

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14. The polishing pad installation tool according to claim 13, wherein when the collar portions of the pins contact the polishing pad, the springs have a greater resistance to compression than the compressible layer.

15. The polishing pad installation tool according to claim 5, wherein the

upper surface of the compressible layer is generally planar.

16. The polishing pad installation tool according to claim 15, wherein the compressible layer includes a resilient high density foam.

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17. The polishing pad installation tool according to claim 5, further comprising a second compressible layer in operative connection with the base portion opposed from the first compressible layer.

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18. A method of installing a polishing pad on a polishing platen comprising:

a) placing a first polishing pad between a first polishing platen and a first side of a polishing tool, wherein the adhesive layer of the first polishing pad is adjacent the first polishing platen;

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b) placing a plurality of pins of the polishing tool into a plurality of holes in the first polishing pad, wherein each of the pins of the polishing tool includes a collar portion;

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c) adhesively bonding the first polishing pad to the first polishing platen, including pressing the first side of the polishing tool against the first polishing pad; and

d) adhesively sealing a plurality of edges of the holes in the first polishing pad to the first polishing platen, including pressing the collar portions of each of the pins adjacent the hole edges of the first polishing pad.

5 19. The method according to claim 18, wherein step (c) includes forcing air out from between the first polishing pad and the first polishing platen, and compressing a first compressible layer of the first side of the polishing tool adjacent a first polishing surface of the first polishing pad.

10 20. The method according to claim 19, wherein prior to step (c) further comprising:

 placing a second polishing pad between a second polishing platen and a second side of the polishing tool that is opposed from the first side of the polishing tool, wherein the adhesive layer of the second polishing pad is adjacent the second polishing platen; and

 wherein step (c) includes adhesively bonding the second polishing pad to the second polishing platen, including pressing the second side of the polishing tool against the second polishing pad.

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 21. The method according to claim 20, wherein step (c) includes decreasing the distance between the first and second polishing platens.

 22. The method according to claim 18, further comprising:

aligning at least one pin of the polishing tool with at least one hole in the
first polishing platen.